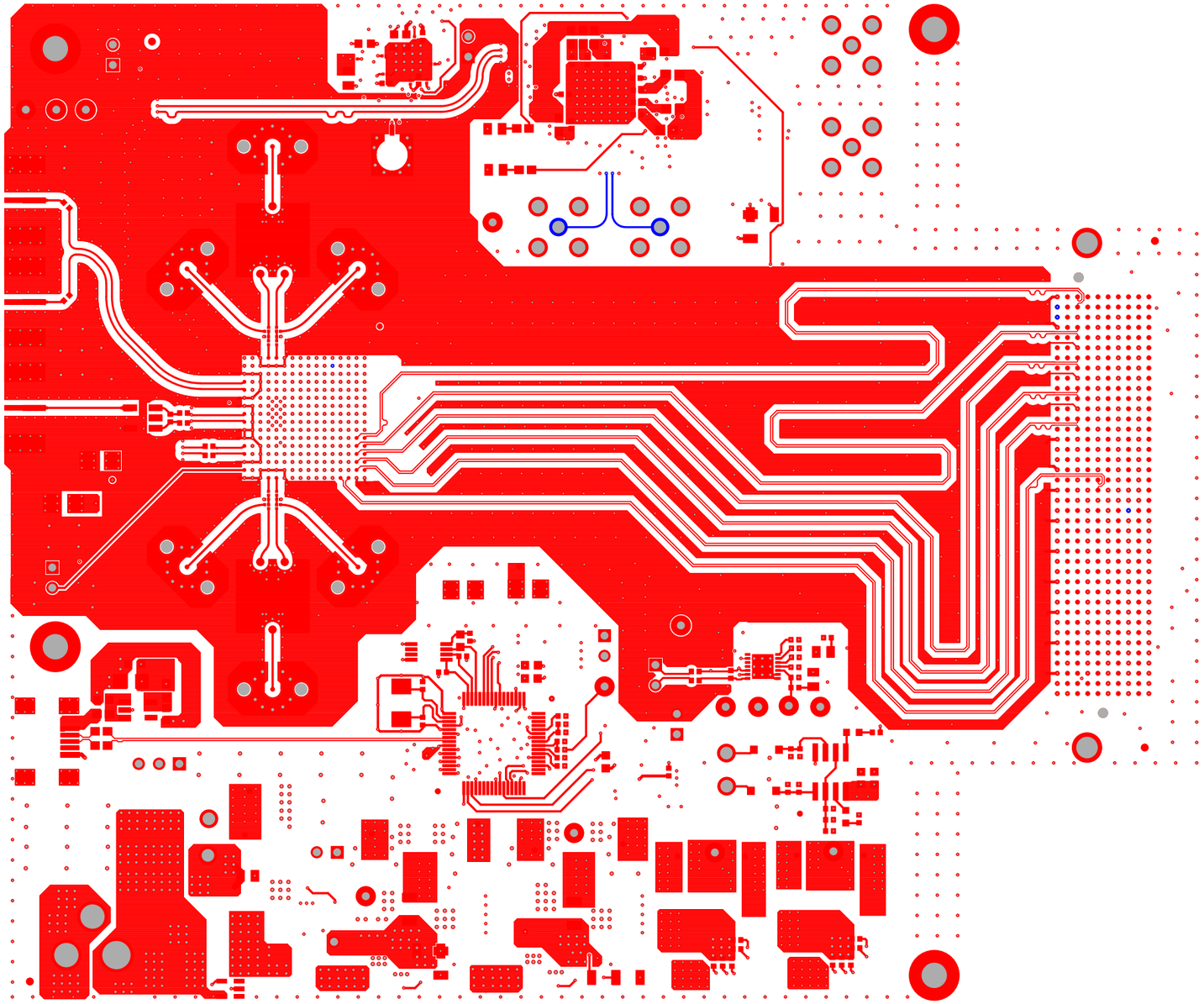
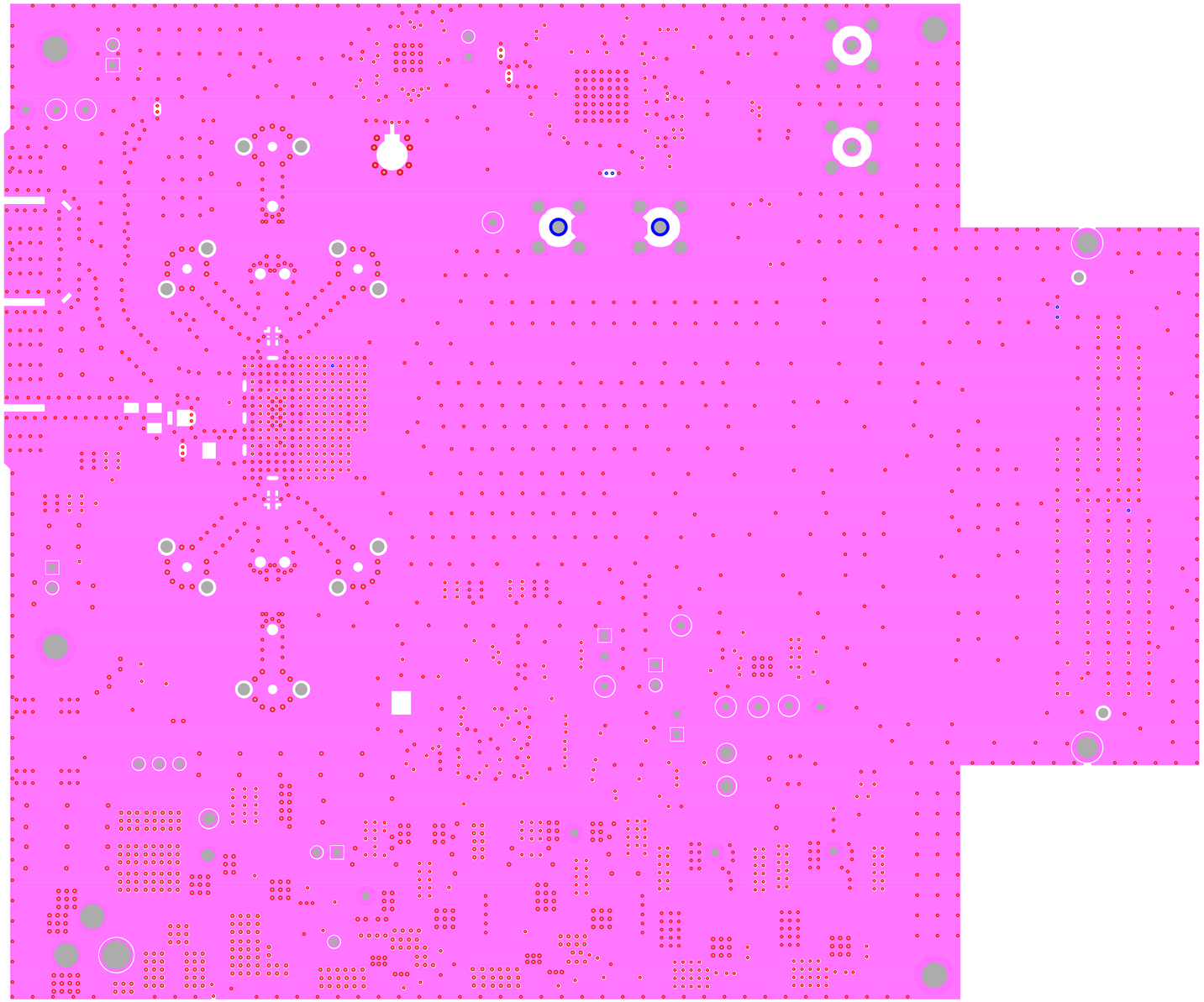


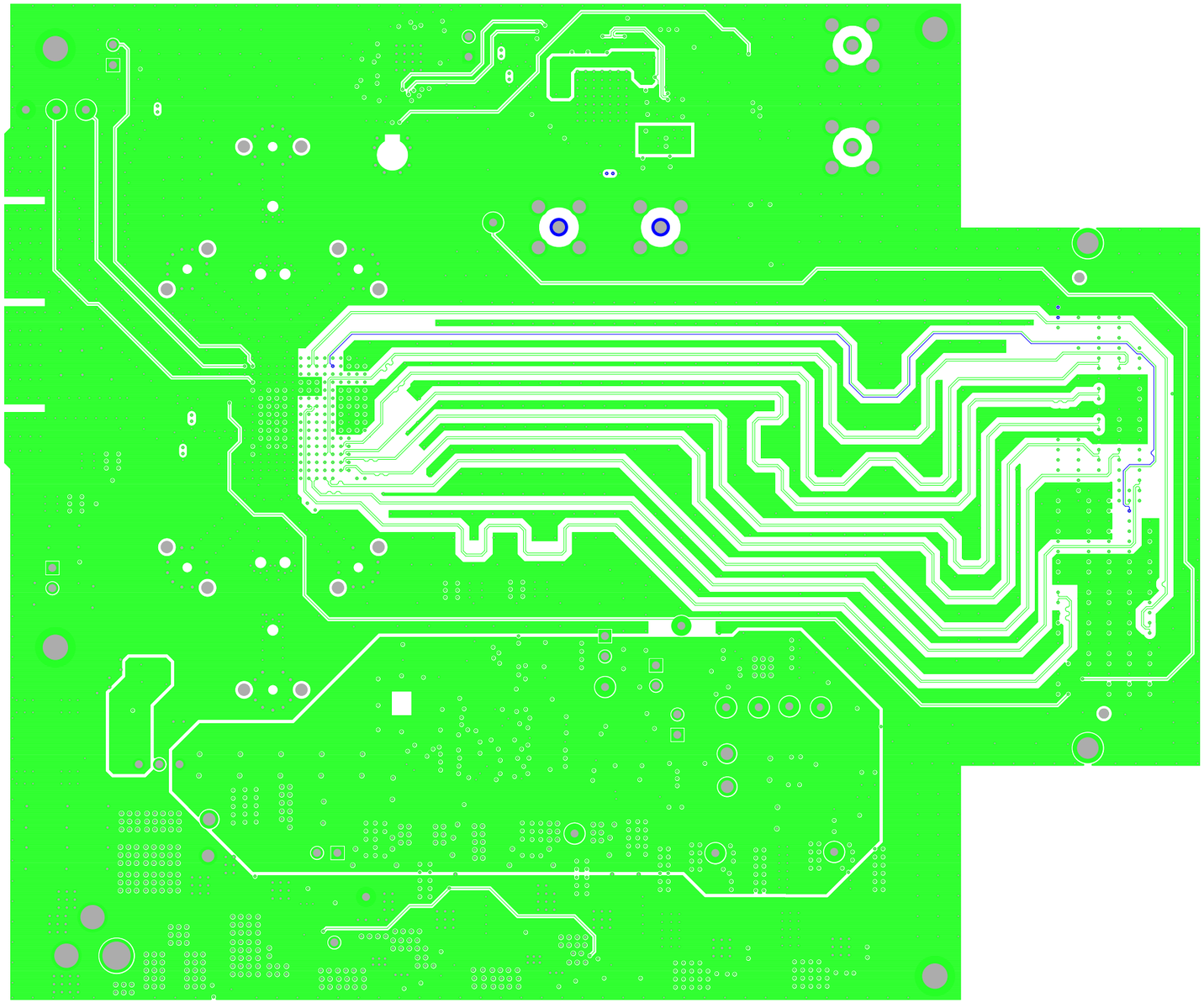
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 1 (TOP SIDE)



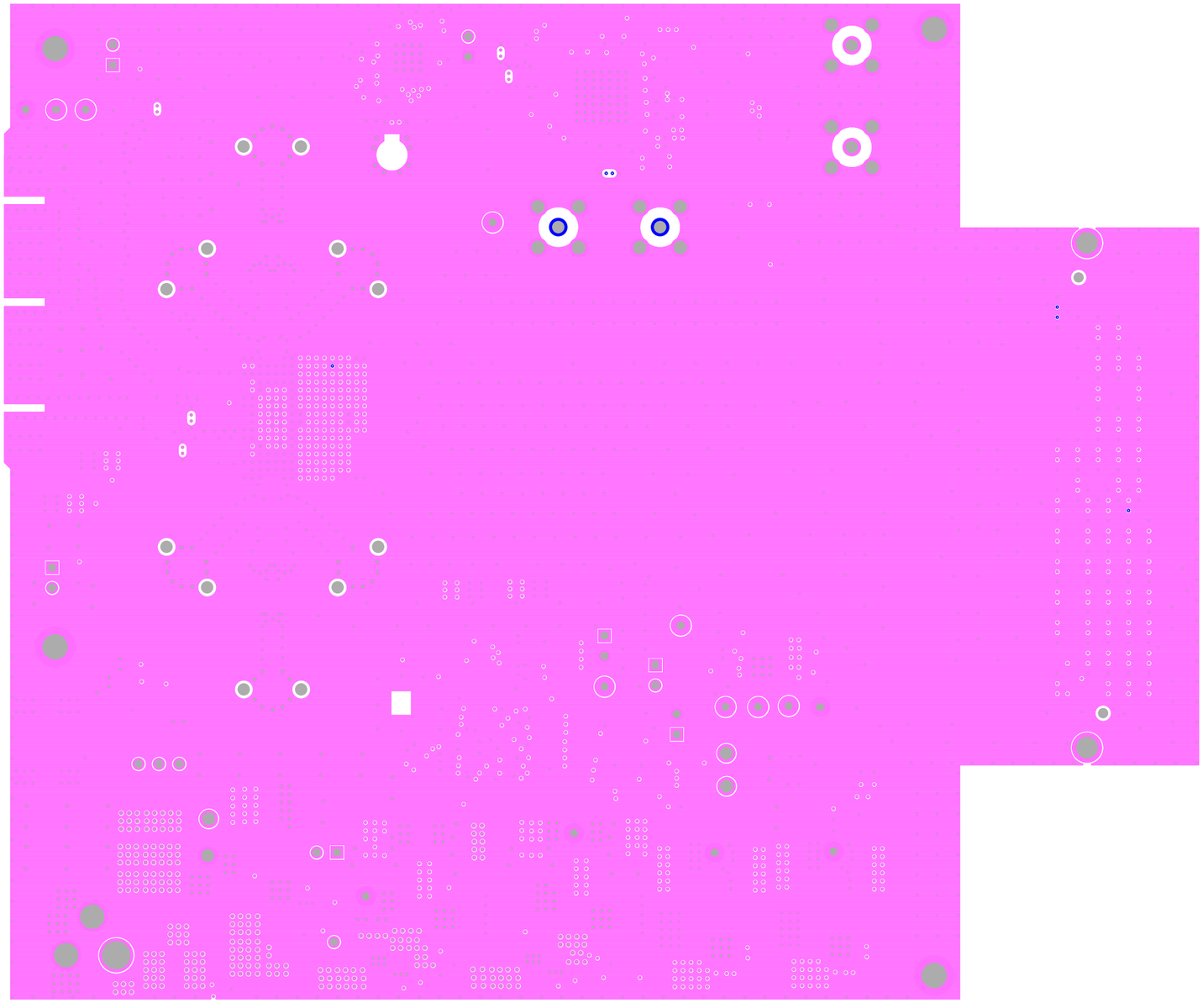
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 2 - GND1



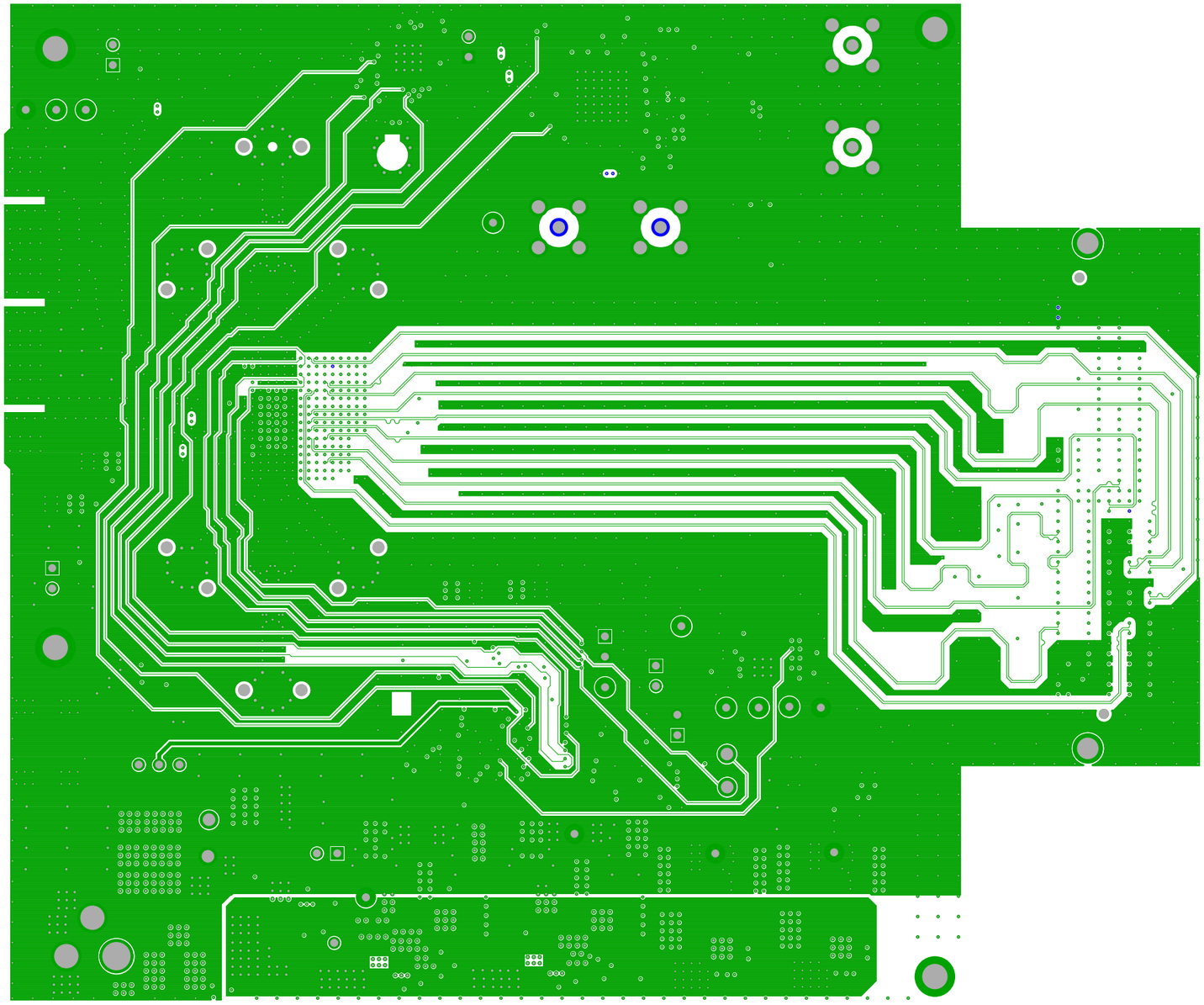
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 3 - SIG1



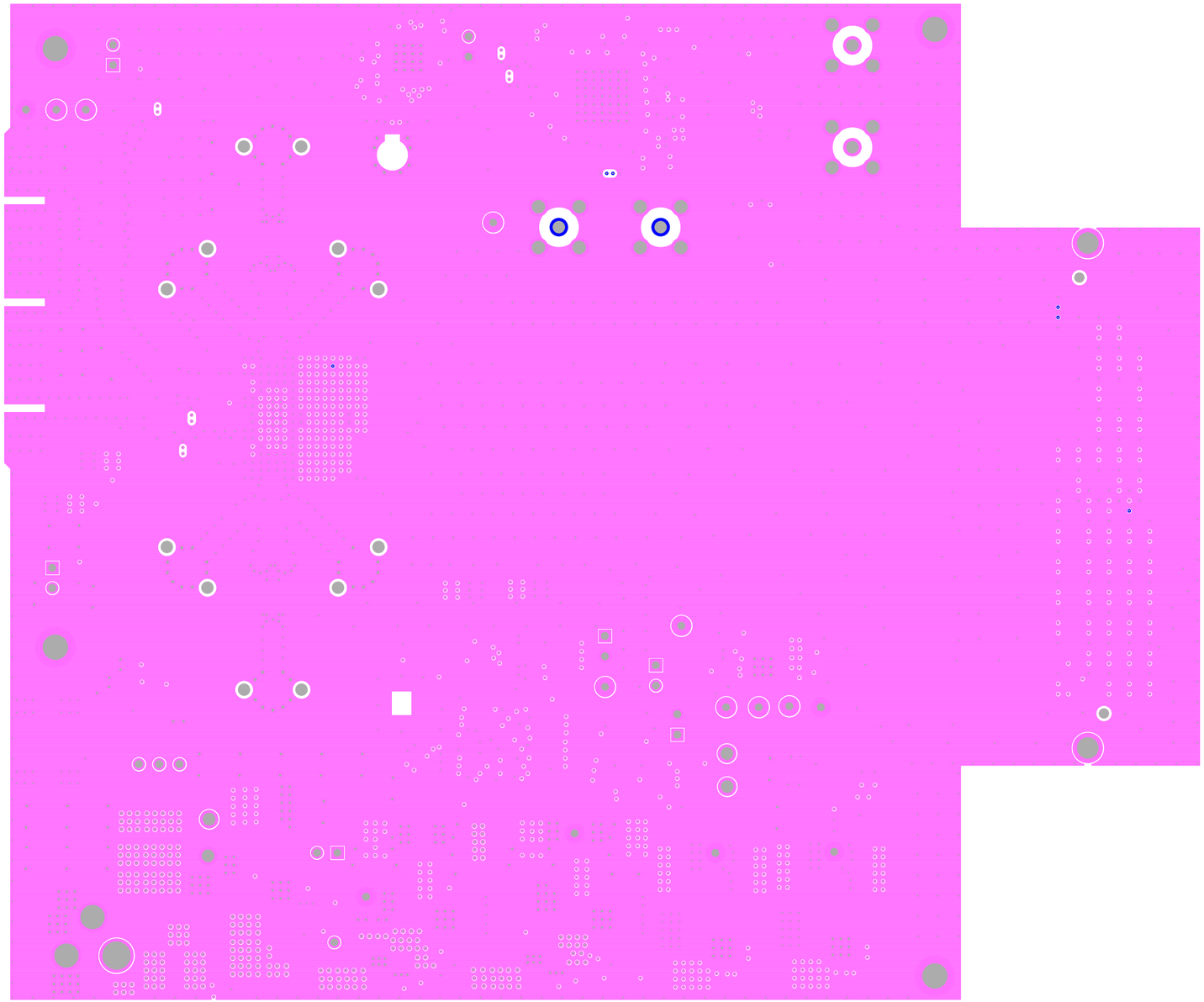
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 4 - GND2



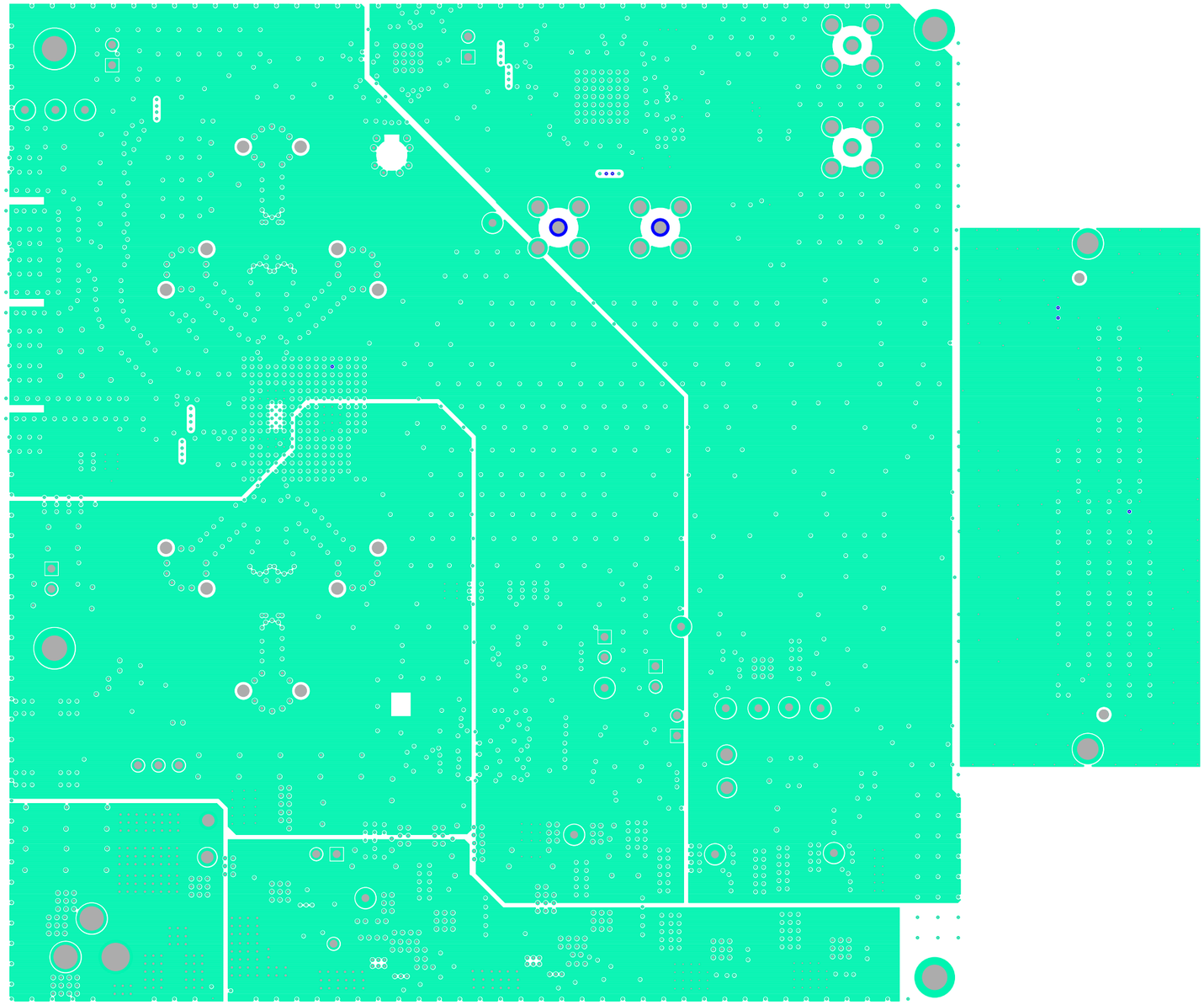
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 5 - SIG2



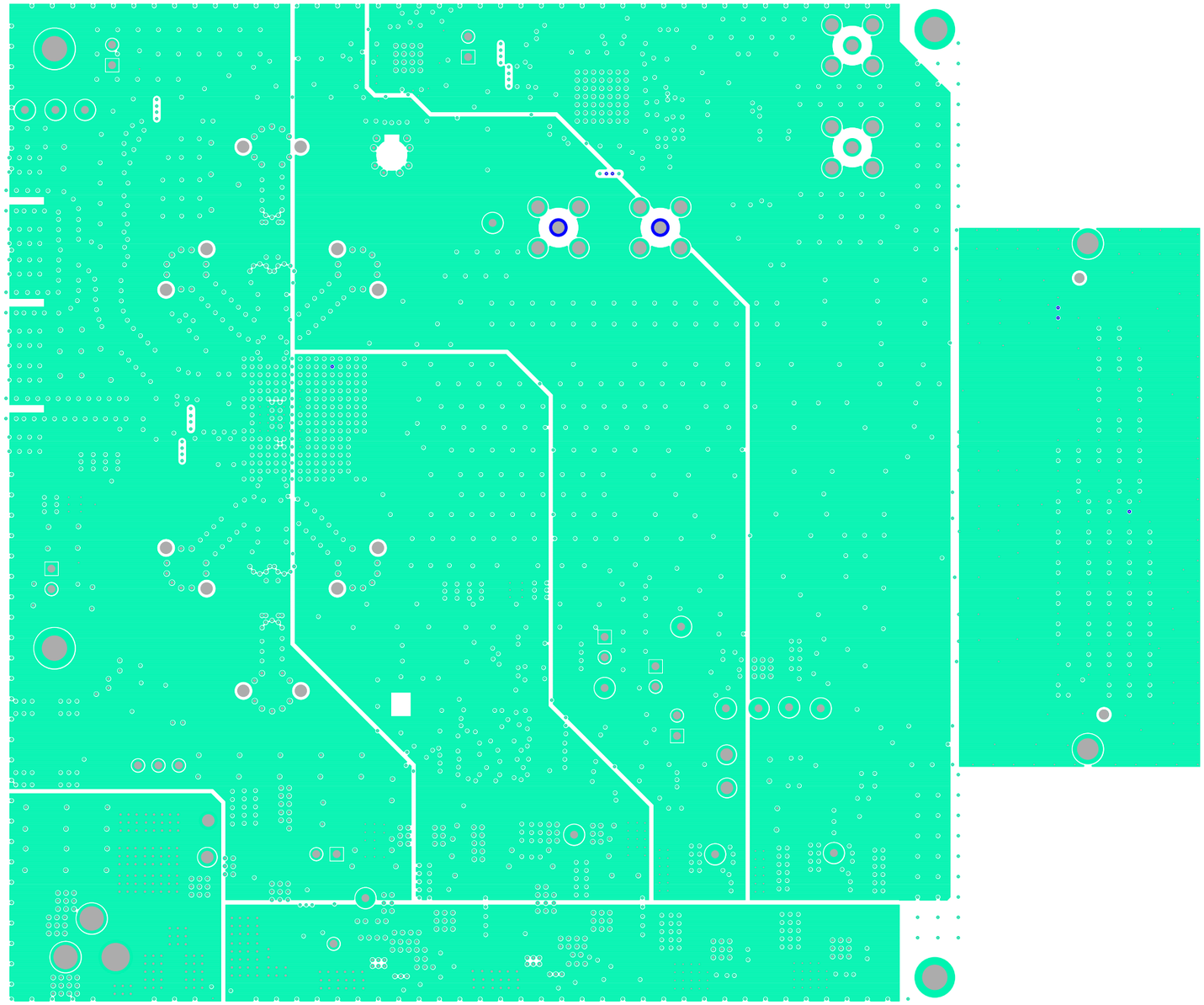
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 6 - GND3



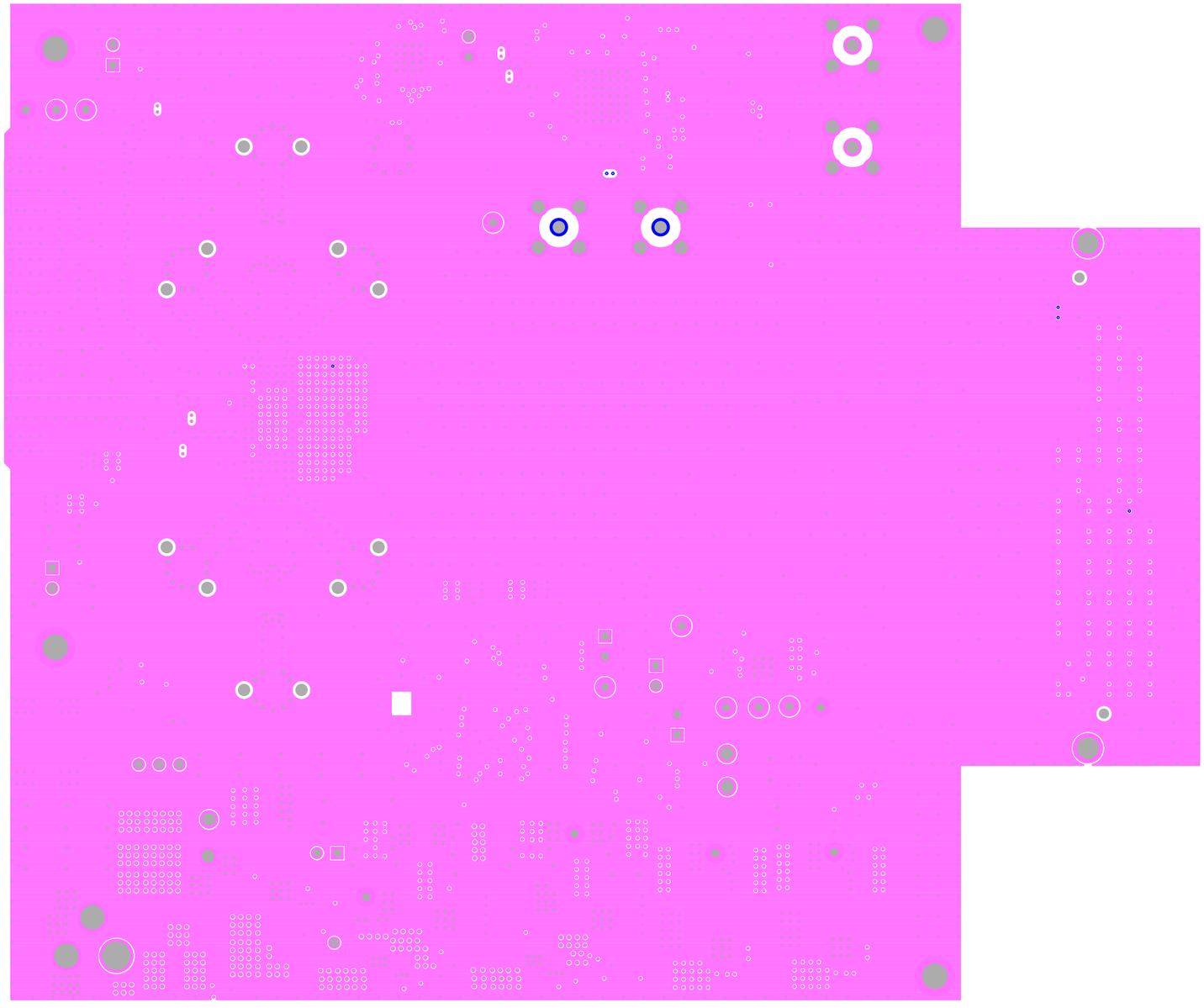
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 7 - PWR1



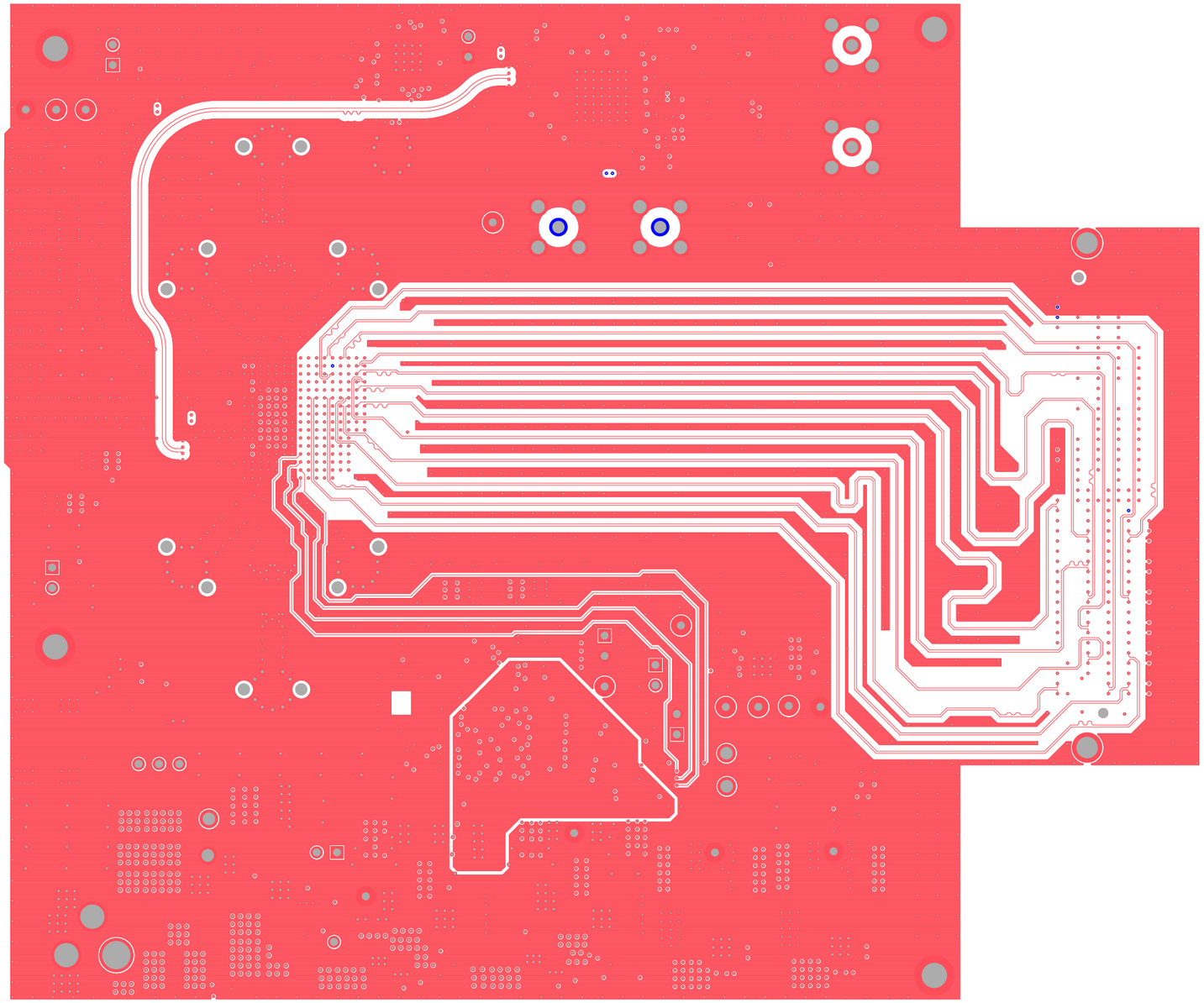
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 8 - PWR2



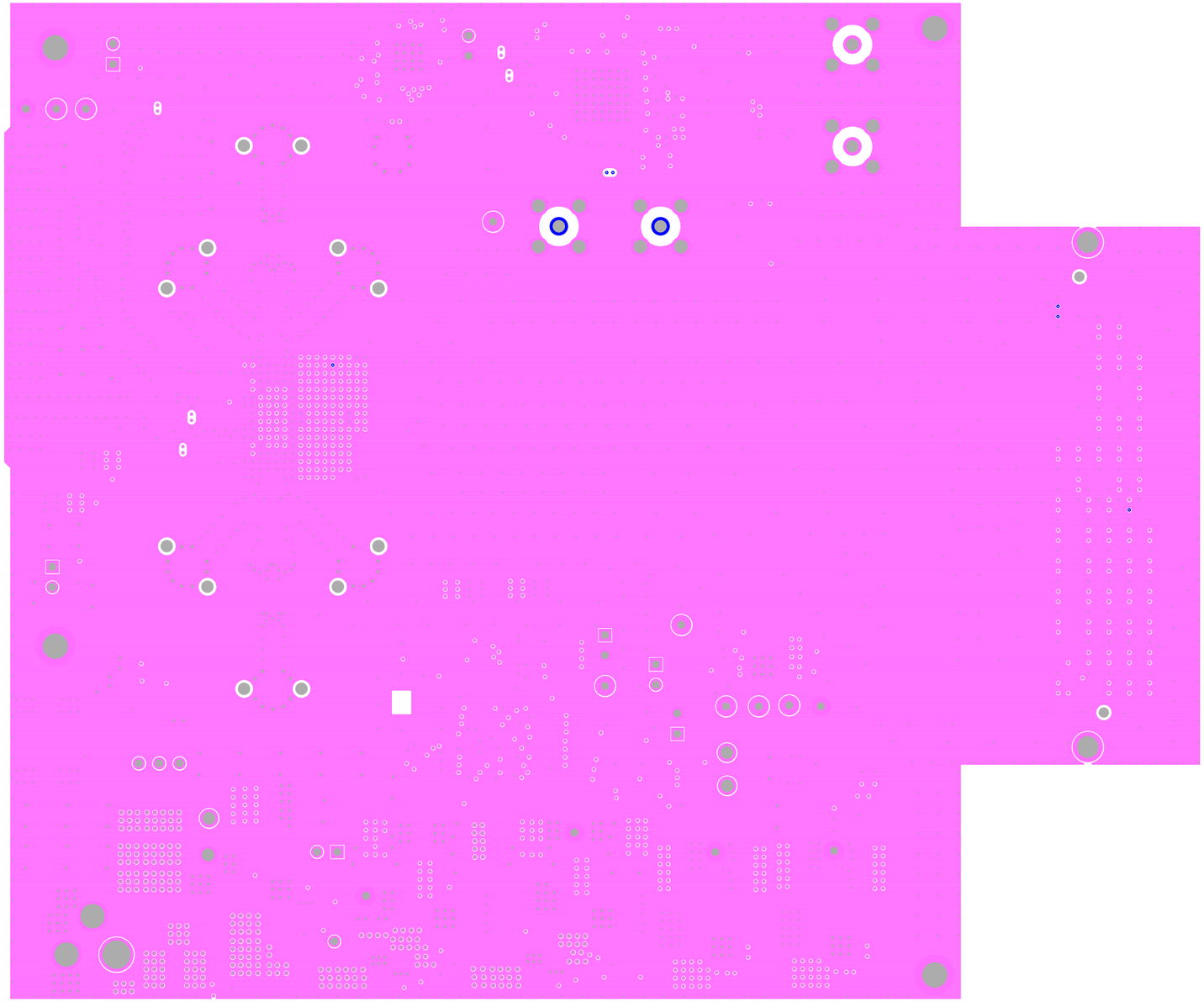
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 9 - GND4



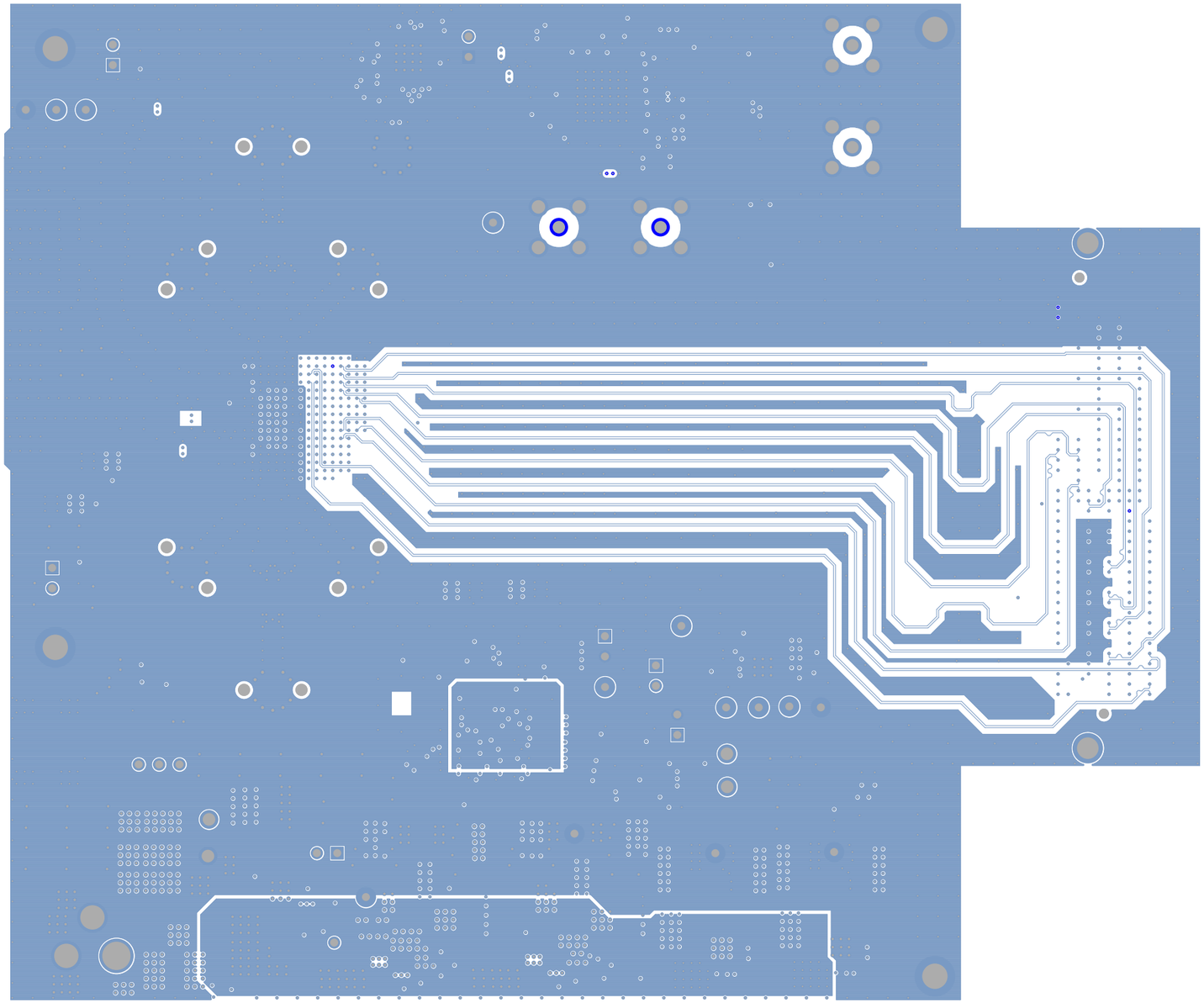
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 10 - SIG3



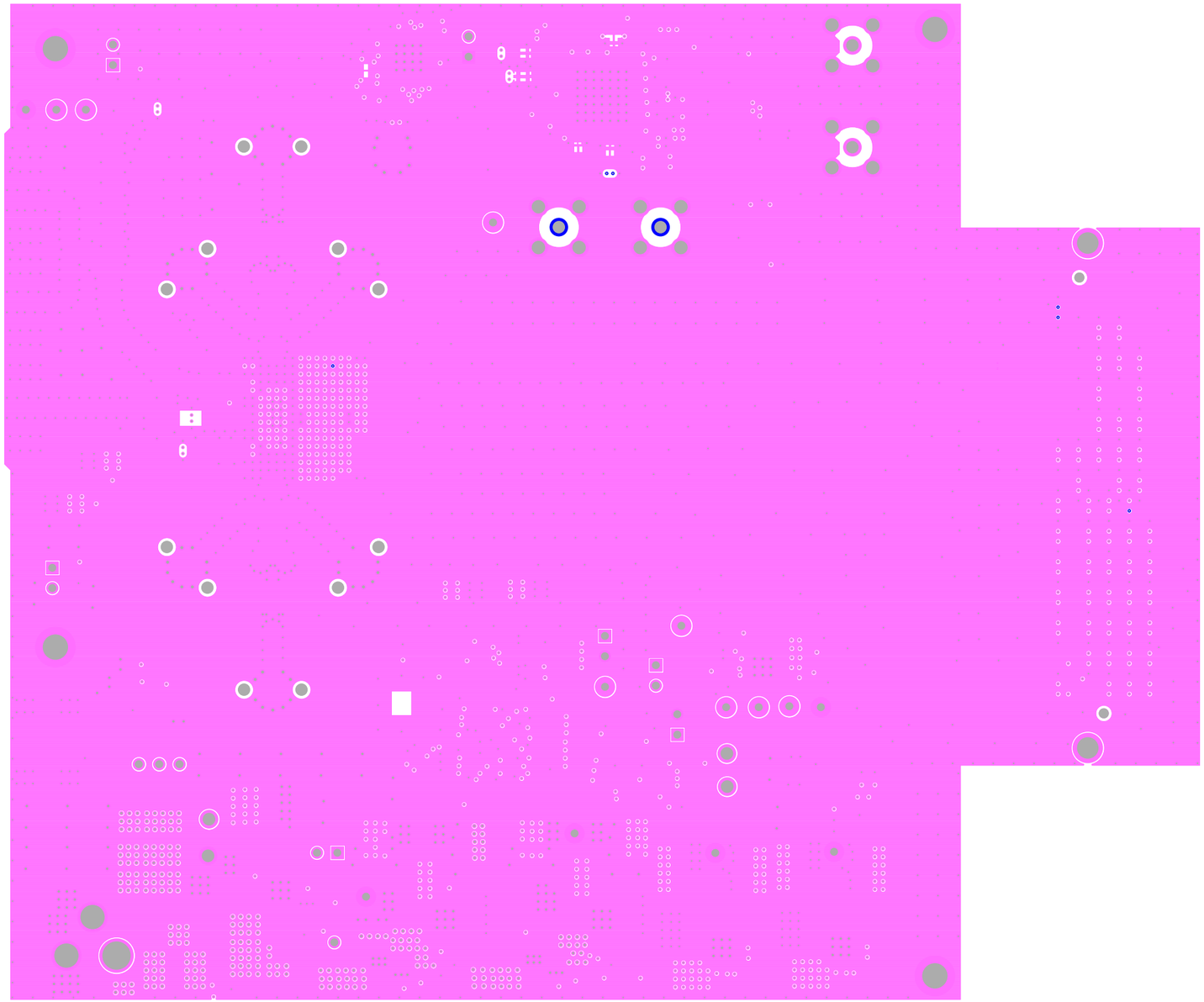
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 11 - GND5



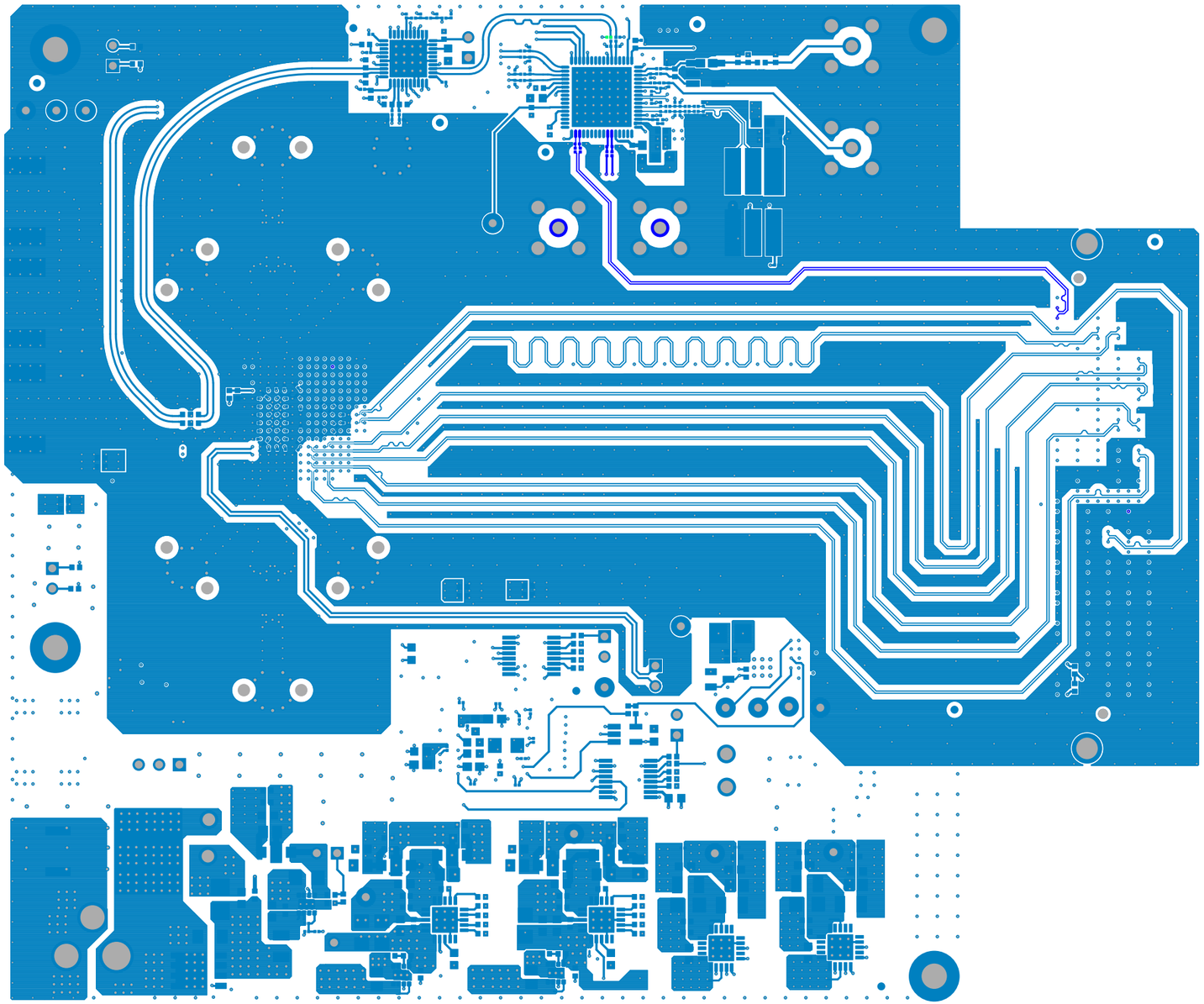
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 12 - SIG4



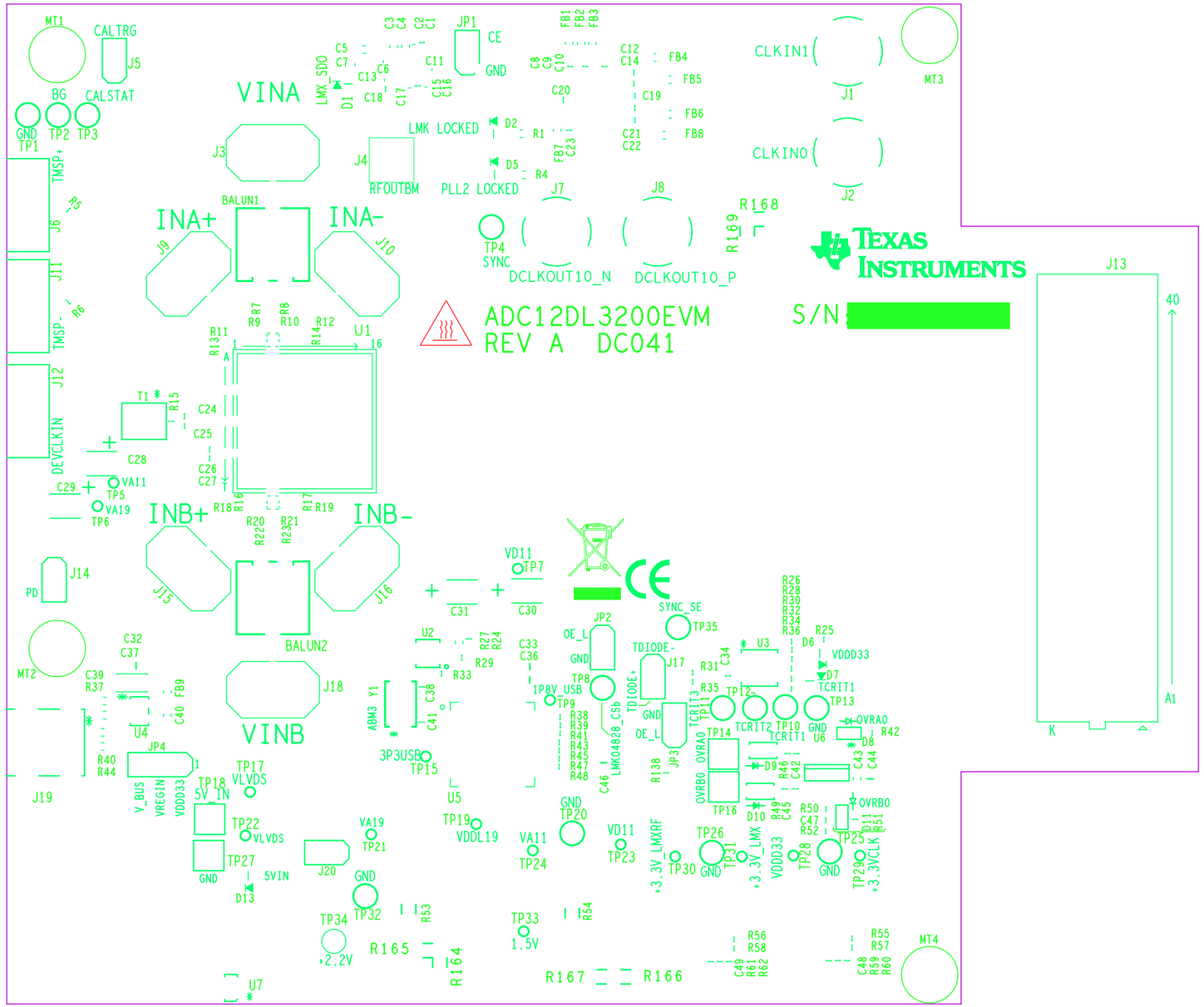
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 13 - GND6



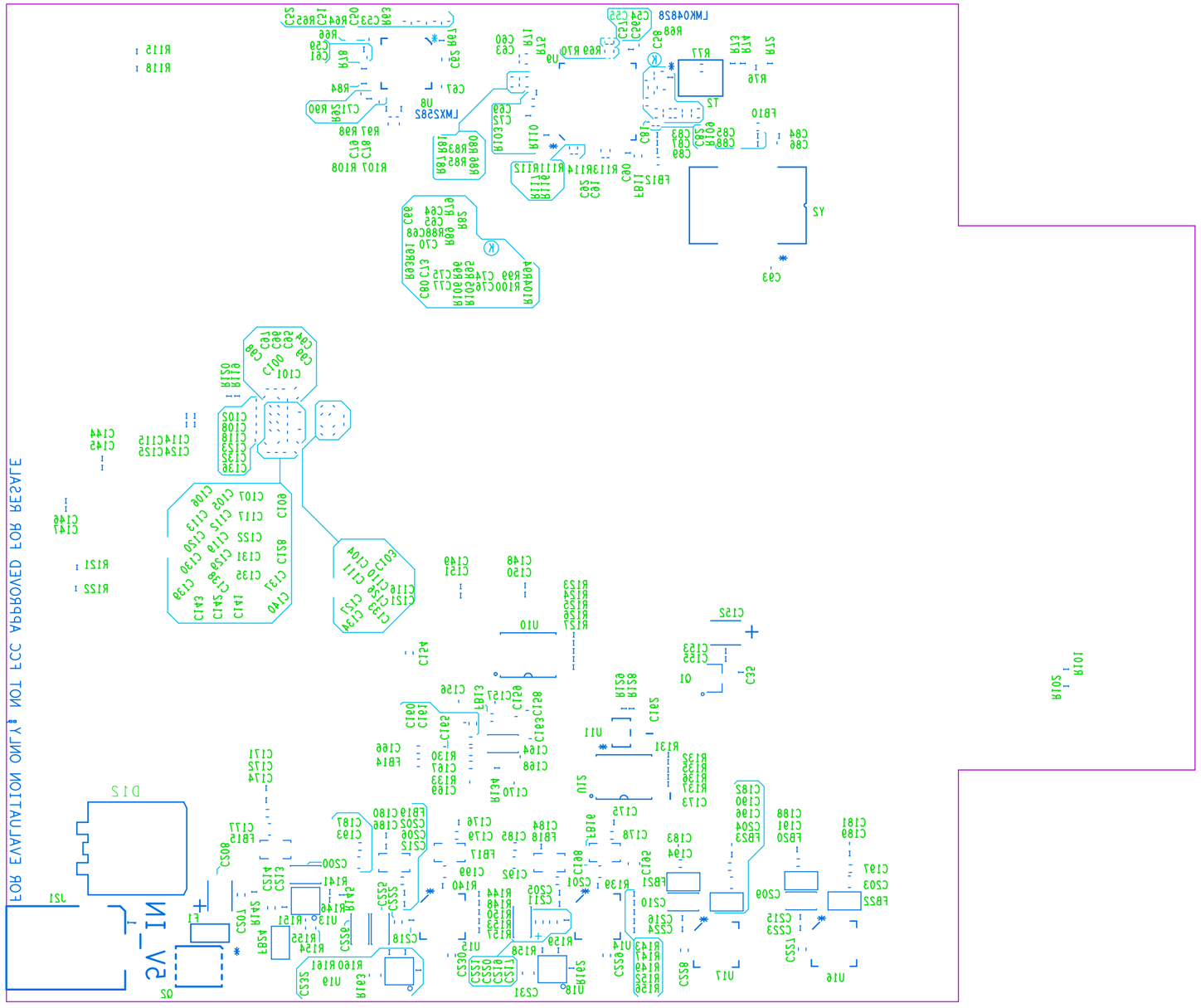
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

LAYER 14 (BOTTOM SIDE)



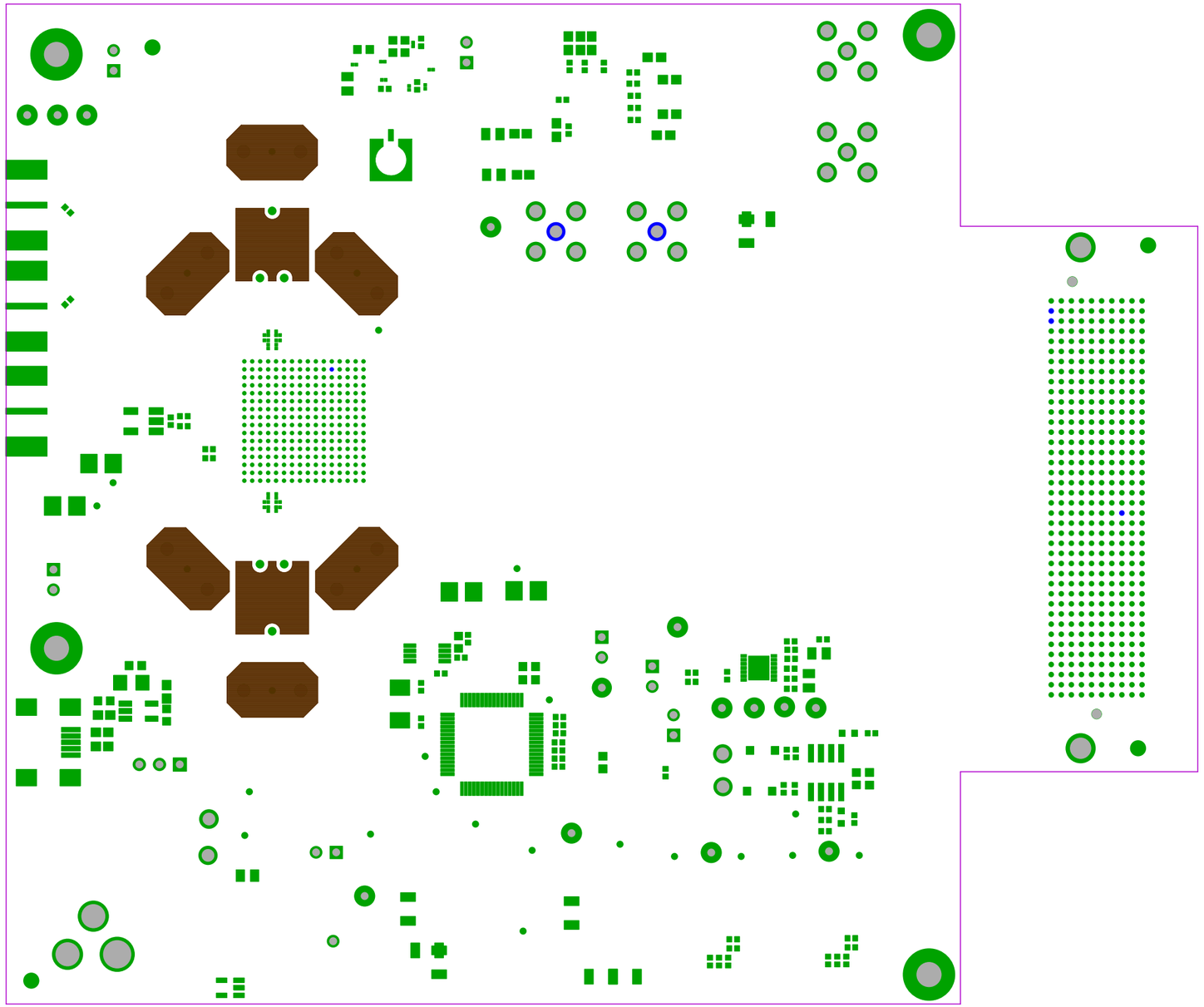
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

SILKSCREEN TOP



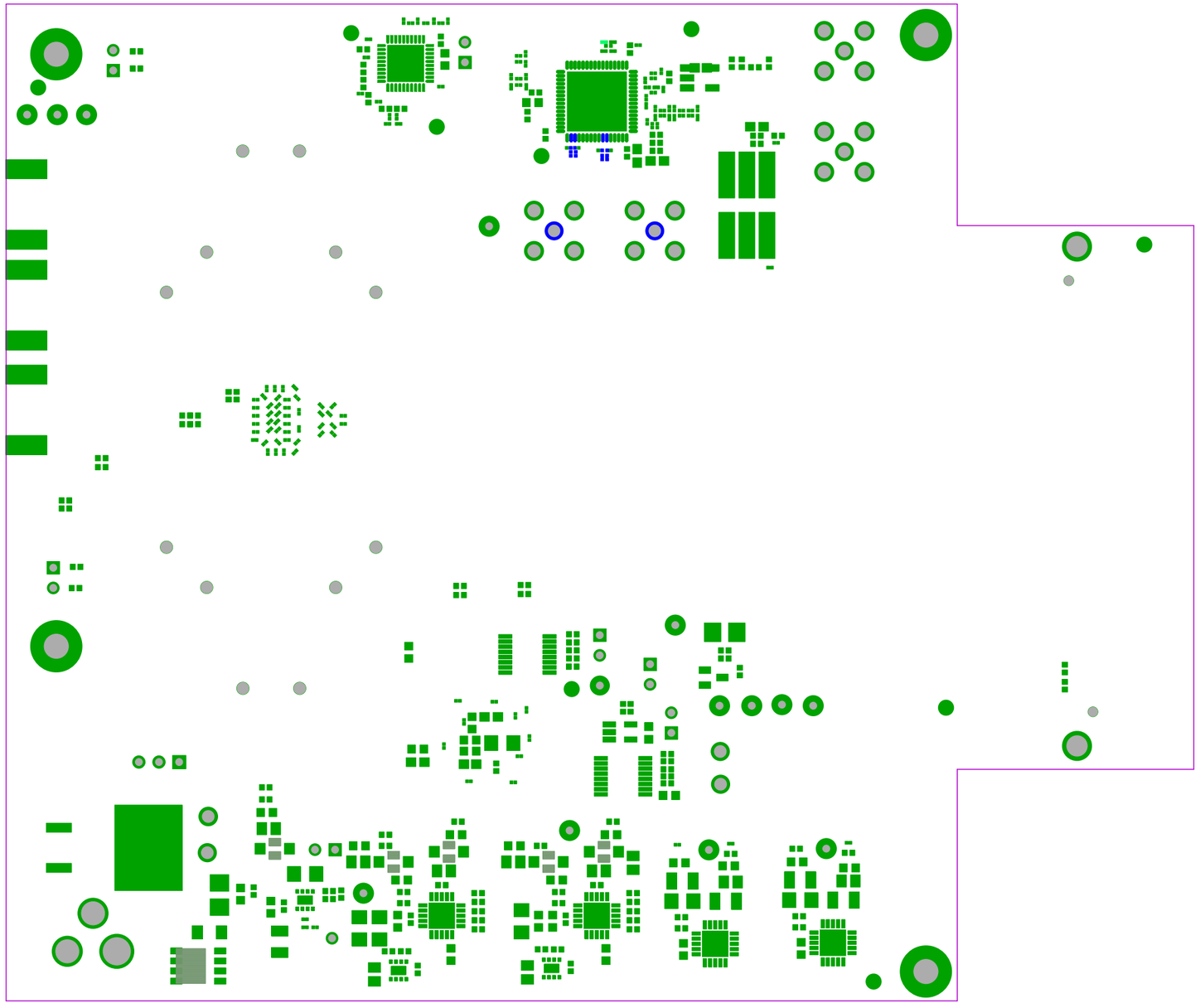
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

SILKSCREEN BOTTOM



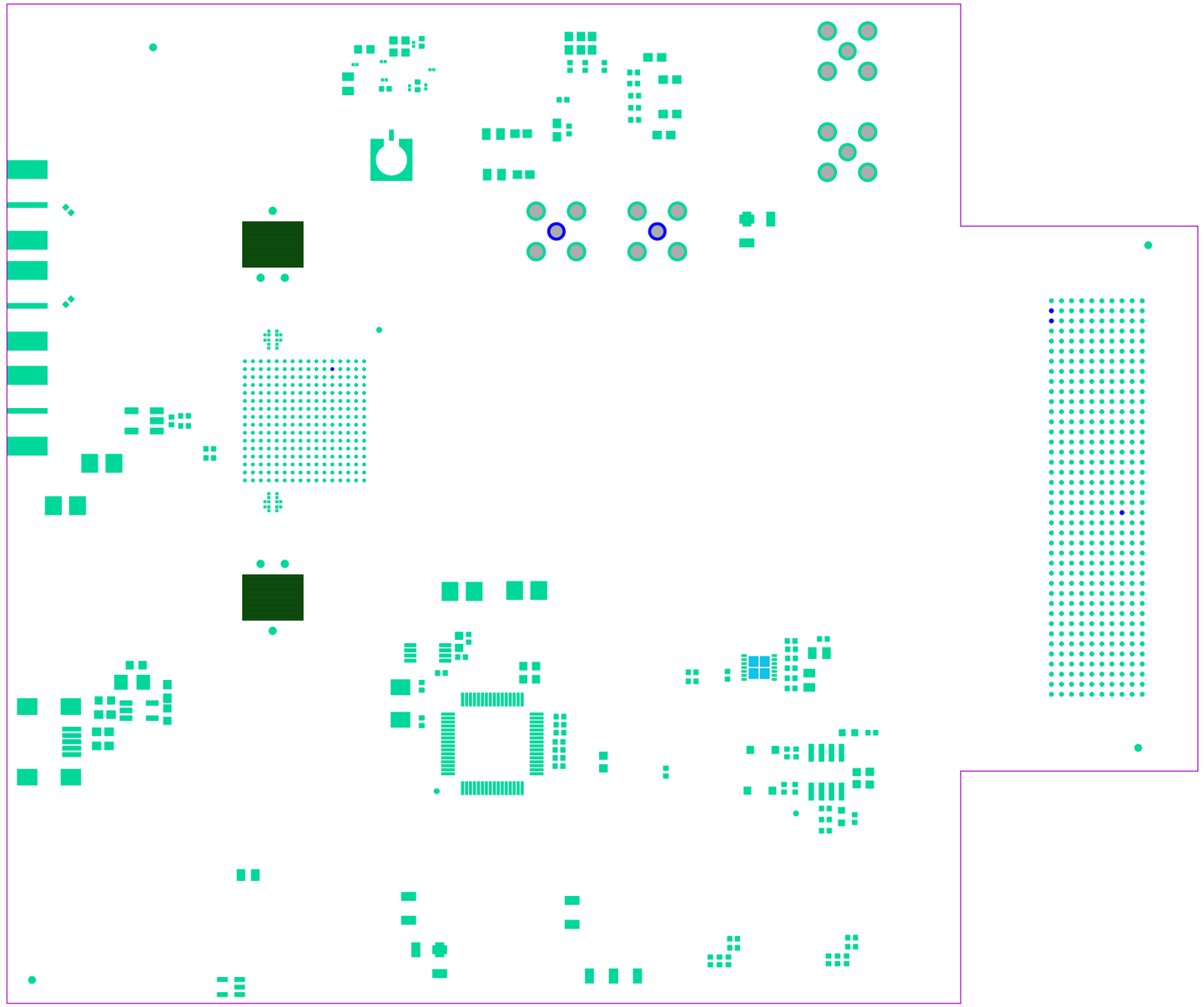
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

SOLDERMASK TOP



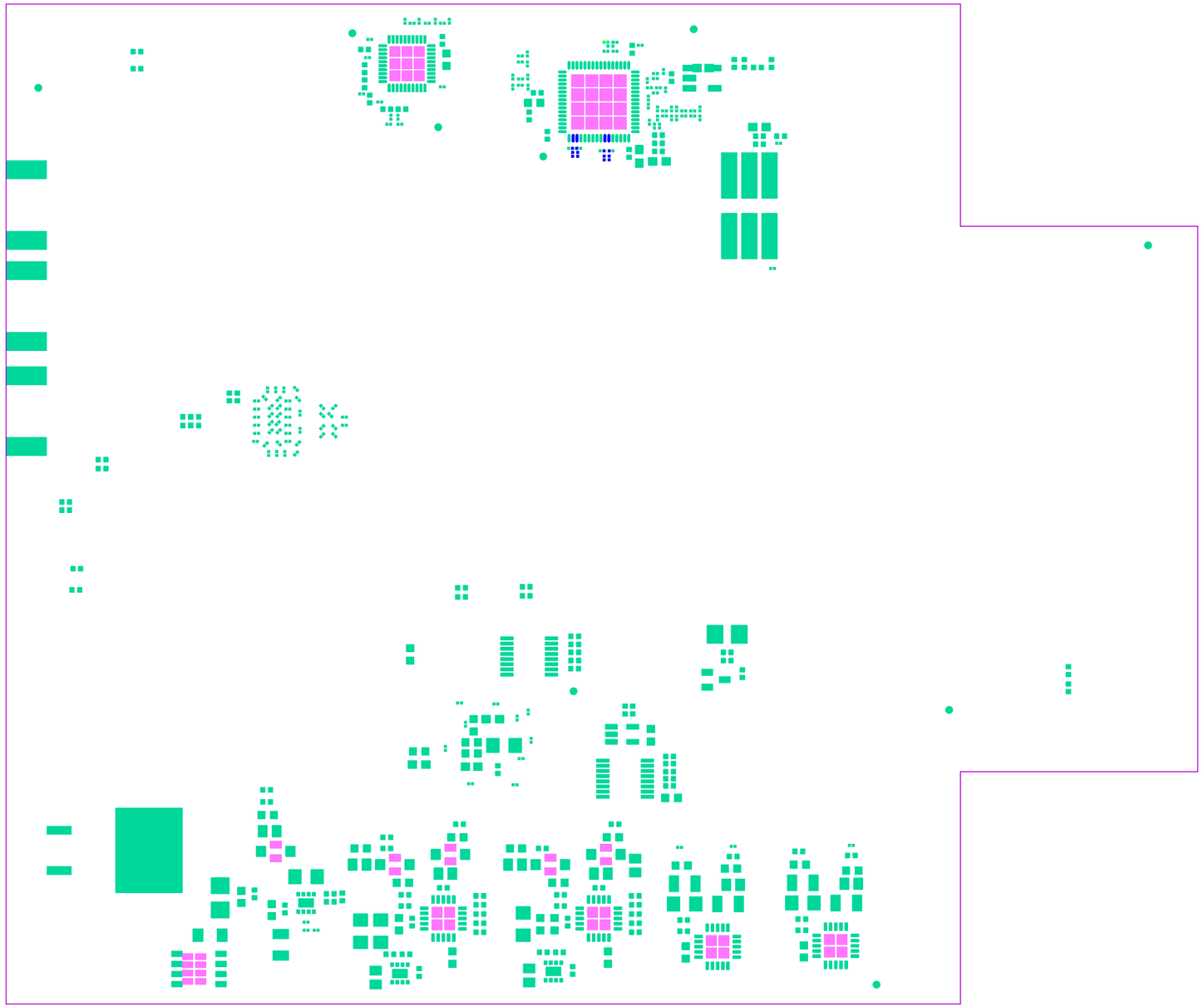
TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

SOLDERMASK BOTTOM



TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

PASTEMASK TOP



TEXAS INSTRUMENTS, INC.
ADC12DL3200EVM DC041 REV A

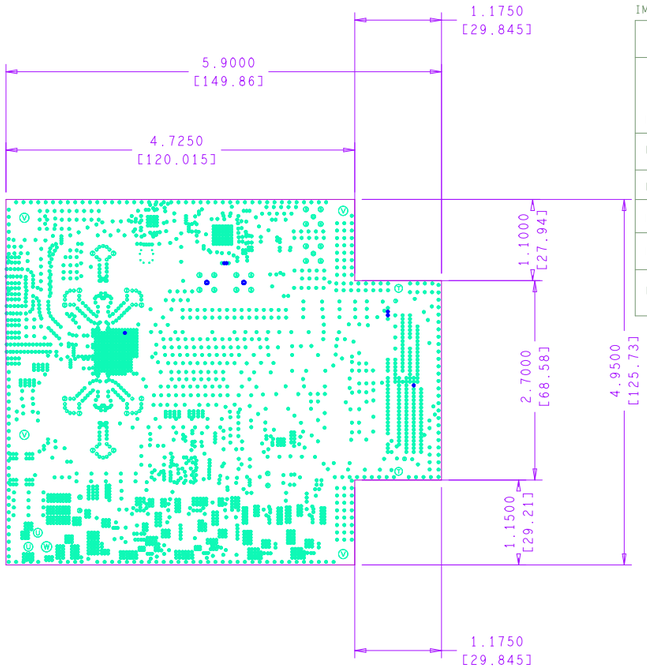
PASTEMASK BOTTOM

UNLESS OTHERWISE SPECIFIED, ALL NOTES ARE APPLICABLE.

1. APPLICATION DESIGN, MANUFACTURING AND INSPECTION DOCUMENTS.
   IPC-2221A & IPC-2222 / DESIGN STANDARD FOR RIGID PRINTED CIRCUIT BOARDS AND RIGID PRINTED BOARD ASSEMBLIES.
   IPC-6012 / QUALIFICATION AND PERFORMANCE SPECIFICATION FOR RIGID PRINTED BOARD, CLASS 2, CURRENT REVISION.
   IPC-A-600 / ACCEPTABILITY OF PRINTED BOARDS, CLASS 2, CURRENT REVISION.
2. VIA SIZE APPLY AFTER PLATING. TOLERANCE TO BE +.003/-.010.
   HOLE SIZE APPLY AFTER PLATING. TOLERANCE TO BE +/-.003.
3. REGISTRATION TOLERANCE: ARTWORK +/- .002.
   ALL HOLE CENTERS +/-.005 FROM DIMENSION DATUM.
4. MINIMUM COPPER WALL THICKNESS SHALL BE .001 INCH.
   FOR ALL PLATED THROUGH HOLES. BREAKOUT NOT ALLOWED.
5. PROCESS AND MATERIAL MUST CONFORM TO UL 796. MATERIAL MUST MEET OR EXCEED UL FLAMMABILITY RATING 94V-0.
   MATERIAL: MULTI-LAYER (SEE DETAIL 'A')
   SEE LAYER STACKUP FOR ALL PRE-PREG & CORE THICKNESSES, COPPER OZ AND MATERIAL. FINISHED BOARD THICKNESS: .062 +/- 10%
6. MANUFACTURE'S UL MARKING, FLAMMABILITY RATING, LOGO AND DATE CODE TO BE PLACED IN SILKSCREEN ON BOTTOM SIDE OF THE BOARD.
7. SMOBC/IMMERSION GOLD: 2 - 5 uIN OVER 118-236 uIN NICKEL PLATING.
8. SOLDERMASK BOTH SIDES USING TAIYO (OR EQUIVALENT) COLOR = RED.
9. SILKSCREEN BOTH SIDES USING WHITE NPI LEADFREE.
   REGISTRATION TOLERANCE TO BE +/-.005.
   INK IS NOT ALLOWED ON EXPOSED PLATED AREA.
10. P.C. BOARD TO BE FREE OF DIRT, OIL, FINGER PRINTS, ETC.
11. BOARD WARPAGE: WARP AND TWIST SHALL NOT EXCEED .007 INCH PER INCH MEASURED AT ANY LOCATION OR DIRECTION ON THE BOARD.
12. BOARD MUST BE 100% ELECTRICALLY TESTED TO ENSURE NO SHORTS OR OPEN CIRCUITS AT 20V.
13. MINIMUM COPPER CONDUCTOR WIDTH IS: 3.4 MIL
    MINIMUM COPPER CONDUCTOR SPACING IS: 3.5MIL.
14. ALL INNER LAYER UNCONNECTED PADS SHALL BE REMOVED.
15. PWB MUST BE ROHS COMPLIANT AND SURVIVE LEAD FREE ASSEMBLY, MAX REFLOW OF 260 DEGREES C (6 PASSES).
16. ALL THROUGH VIAS TO BE PLUGGED WITH NON-CONDUCTIVE EPOXY MATERIAL. PLUGGED VIAS TO BE PLATED AFTER PLUGGING TO PRESENT FLAT SURFACE TO DEVICE. NO POTHOLES.
17. BOARD DIMENSIONS ARE IN INCHES (MM).
18. ALL HOLES LESS THAN 12 MIL ARE NOT FINISHED HOLE SIZE

DRILL CHART: TOP to BOTTOM
ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY	
•	8.0	+3.0/-3.0	PLATED	2002	NOTE 16
•	10.0	+3.0/-3.0	PLATED	91	NOTE 16
•	12.0	+3.0/-3.0	PLATED	504	NOTE 16
·	16.0	+3.0/-3.0	PLATED	8	NOTE 16
•	16.0	+3.0/-3.0	PLATED	53	
•	40.0	+3.0/-3.0	PLATED	14	
•	40.0	+3.0/-3.0	PLATED	18	
⊕	62.0	+3.0/-3.0	PLATED	4	
⊕	63.0	+3.0/-3.0	PLATED	4	
⊕	67.0	+3.0/-3.0	PLATED	16	
Ⓣ	106.0	+3.0/-3.0	PLATED	2	
Ⓤ	120.0	+3.0/-3.0	PLATED	2	
Ⓥ	125.0	+3.0/-3.0	PLATED	4	
Ⓦ	140.0	+3.0/-3.0	PLATED	1	
⊕	50.0	+2.0/-0.0	NON-PLATED	2	
⊕	62.0	+2.0/-0.0	NON-PLATED	12	



IMPEDANCE TABLE.

	50 OHM SINGLE ENDED		100 OHM DIFFERENTIAL TIGHTLY COUPLED			100 OHM DIFFERENTIAL LOOSELY COUPLED		
	TRACE WIDTH (MILS)	TOL (%)	TRACE WIDTH (MILS)	SPACING (MILS)	TOL (%)	TRACE WIDTH (MILS)	SPACING (MILS)	TOL (%)
L01_TOP	11	5 %	6	5	10 %	10	18	10 %
L03_SIG1	3.5	10 %	3.4	6.6	10 %	—	—	—
L05_SIG2	3.5	10 %	3.4	6.6	10 %	—	—	—
L10_SIG3	3.5	10 %	3.4	6.6	10 %	3.6	13	10 %
L12_SIG4	—	—	3.4	6.6	10 %	—	—	—
L12_BOTTOM	11	5 %	6	5	10 %	10	18	10 %

DETAIL 'A'

LAYER	THICKNESS	PRIMARY STACKUP	DESCRIPTION
SOLDERMASK TOP	0.0005		Taiyo 4000-BN
LAYER 1 TOP	0.0020		1/4oz Sig (Std Plt)
	0.0056	1035-75% / 1035-75%	R-5670K
LAYER 2 GND1	0.0006		1/2oz P/G
	0.0030	0.0030 (1-1078)	R-5775K
LAYER 3 SIG1	0.0006		1/2oz Sig
	0.0039	1078-75%	R-5670K
LAYER 4 GND2	0.0006		1/2oz P/G
	0.0030	0.0030 (1-1078)	R-5775K
LAYER 5 SIG2	0.0006		1/2oz Sig
	0.0038	1078-75%	R-5670K
LAYER 6 GND3	0.0012		1oz P/G
	0.0026	0.0026 (1-1078)	R-5775K
LAYER 7 PWR1	0.0012		1oz P/G
	0.0039	1078-75%	R-5670K
LAYER 8 PWR2	0.0012		1oz P/G
	0.0026	0.0026 (1-1078)	R-5775K
LAYER 9 GND4	0.0012		1oz P/G
	0.0038	1078-75%	R-5670K
LAYER 10 SIG3	0.0006		1/2oz Sig
	0.0030	0.0030 (1-1078)	R-5775K
LAYER 11 GND5	0.0006		1/2oz P/G
	0.0039	1078-75%	R-5670K
LAYER 12 SIG4	0.0006		1/2oz Sig
	0.0030	0.0030 (1-1078)	R-5775K
LAYER 13 GND6	0.0006		1/2oz P/G
	0.0056	1035-75% / 1035-75%	R-5670K
LAYER 14 BOTTOM	0.0020		1/4oz Sig (Std Plt)
SOLDERMASK BOTTOM	0.0005		Taiyo 4000-BN

MATERIALS: PANASONIC R-5670K MEGTRON 6 PREPREG
PANASONIC R-5775K MEGTRON 6

REVISIONS

ZONE	LTR	DESCRIPTION	DATE	APPROVED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
FRACTIONS +/- DECIMALS .XX +/-.01 .XXX +/-.005 ANGLES +/-

MATERIAL: SEE NOTE 5

FINISH: SEE NOTE 7, 8, 9

DO NOT SCALE DRAWING

CONTRACT NO.

APPROVALS	DATE
DRAWN PACTRON	03-13-18
ENG J BRINKHURST	03-13-18

TEXAS INSTRUMENTS INC.

FABRICATION DRAWING
ADC12DL3200EVM

SIZE	CODE IDENT NO.	DRAWING NO.	REV.
D		DC041	A

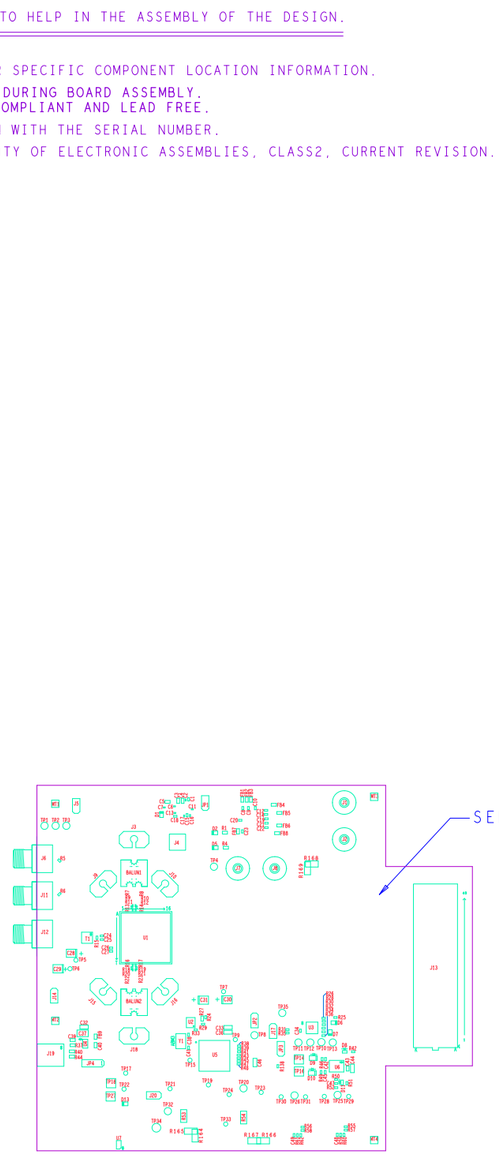
SCALE NONE SHEET 1 OF 1

THIS DRAWING IS INTENDED TO HELP IN THE ASSEMBLY OF THE DESIGN.

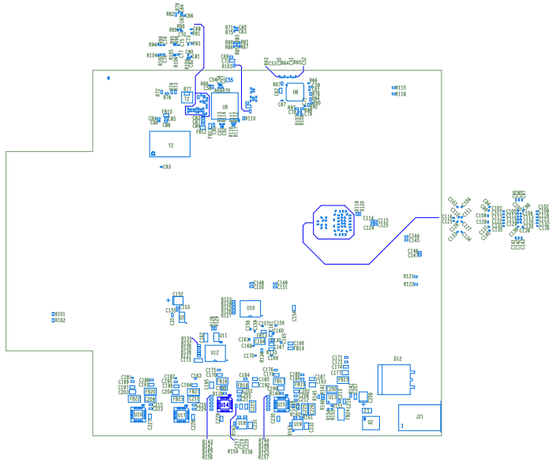
1. REFER TO ODB++ FILE FOR SPECIFIC COMPONENT LOCATION INFORMATION.
2. USE WATER SOLUBLE FLUX DURING BOARD ASSEMBLY.
   ASSEMBLY MUST BE RoHS COMPLIANT AND LEAD FREE.
3. MARK BOARD'S SILKSCREEN WITH THE SERIAL NUMBER.
4. IPC-A-610 / ACCEPTABILITY OF ELECTRONIC ASSEMBLIES, CLASS2, CURRENT REVISION.

REVISIONS

ZONE	LTR	DESCRIPTION	DATE	APPROVED



TOP VIEW



BOTTOM VIEW

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES +/- .XX +/-.01 +/- .XXX +/-.005 +/-	CONTRACT NO.	TEXAS INSTRUMENTS INC.
	APPROVALS / DATE	ASSEMBLY DRAWING ADC12DJ3200 EVM
	DRAWN PACTRON 03-13-18	
	ENGR J BRINKHURST 03-13-18	
MATERIAL SEE NOTE 5		SIZE B / CODE IDENT NO. / DRAWING NO. DC041 / REV. A
FINISH SEE NOTES 7, 8, 9		SCALE 2:1 / SHEET 1 OF 1
DO NOT SCALE DRAWING		